Power Transistors Panasonic

2SB1169, 2SB1169A

Silicon PNP epitaxial planar type

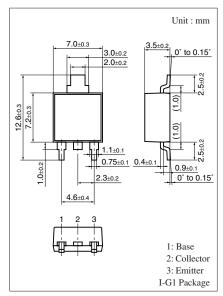
For power amplification

■ Features

- \bullet High forward current transfer ratio $h_{F\!E}$ which has satisfactory linearity
- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SB1169	V _{CBO}	-60	V
(Emitter open)	2SB1169A		-80	
Collector-emitter voltage	2SB1169	V _{CEO}	-60	V
(Base open)	2SB1169A		-80	
Emitter-base voltage (Col	V_{EBO}	-5	V	
Collector current	I_C	-1	A	
Peak collector current	I_{CP}	-2	A	
Collector power dissipation		P _C	15	W
	$T_a = 25$ °C		1.3	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	−55 ~ +150	°C	



Note) Self-supported type package is also prepared.

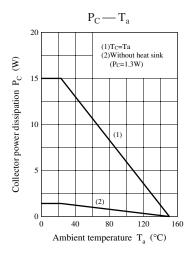
\blacksquare Electrical Characteristics $\,T_{C}=25^{\circ}C\pm3^{\circ}C$

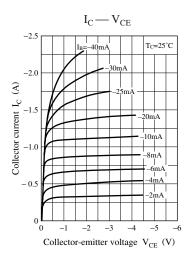
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SB1169	V _{CEO}	$I_C = -30 \text{ mA}, I_B = 0$	-60			V
(Base open)	2SB1169A			-80			
Base-emitter voltage		V_{BE}	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$			-1.3	V
Collector-emitter cutoff	2SB1169	I _{CES}	$V_{CE} = -60 \text{ V}, V_{BE} = 0$			-200	μΑ
current (E-B short)	2SB1169A		$V_{CE} = -80 \text{ V}, V_{BE} = 0$			-200	
Collector-emitter cutoff	2SB1169	I _{CEO}	$V_{CE} = -30 \text{ V}, I_B = 0$			-300	μΑ
current (Base open)	2SB1169A		$V_{CE} = -60 \text{ V}, I_B = 0$			-300	
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0$			-1	mA
Forward current transfer ratio		h _{FE1} *	$V_{CE} = -4 \text{ V}, I_{C} = -0.2 \text{ A}$	40		450	_
		h _{FE2}	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$	15			
Collector-emitter saturation voltage		V _{CE(sat)}	$I_C = -1 A, I_B = -0.125 A$			-1	V
Transition frequency		f_T	$V_{CE} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, f = 10 \text{ MHz}$		40		MHz
Turn-on time		t _{on}	$I_C = -1 \text{ A}, I_{B1} = -50 \text{ mA}, I_{B2} = 50 \text{ mA}$		0.5		μs
Strage time		t _{stg}	$V_{CC} = -50 \text{ V}$		1.2		μs
Fall time		t_{f}			0.3		μs

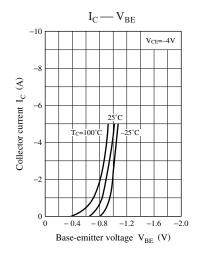
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

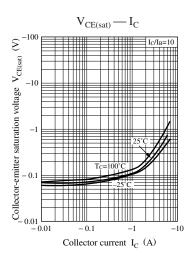
2. *: Rank classification

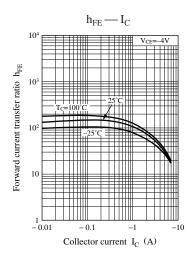
Rank	R	Q	Р	0
h _{FE1}	40 to 90	70 to 150	120 to 250	200 to 450

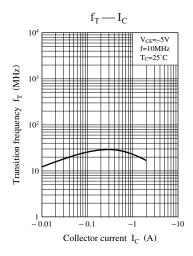


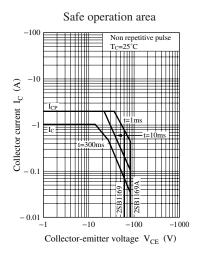


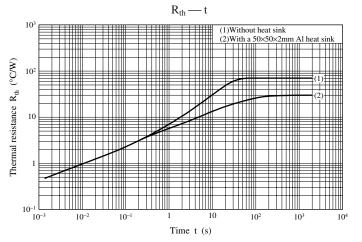












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